					SHEET 12	OF <u>26</u>		
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	3 2005 50 10		,	APPLICANT Alexander T. SCHWARM et al.				
STENT &	TRANEMARK			FILING DATE August 1, 2003	GROUP 2812			
			U.S. PATEN	Γ DOCUMENTS				
EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS CLASS			
	09/363,966		Arackaparambil et al.	Computer Integrated Manufactor Techniques				
-	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium				
	09/619,044	07/19/00	Yuan	System and Method of Exporting Importing Object Data in a Man Execution System				
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder				
	09/656,031	09/06/00	Chi et al.	Dispatching Component for As Manufacturing Facility Service with Service Providers				
	09/655,542	09/06/00	Yuan	System, Method and Medium for Palettes to Transform an Application Program Interface for a Service	cation			
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems				
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task (Guide			
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated C Software Workflow	_			
	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer Pro- in Semiconductor Manufacturin	ng Processes			
	09/928,473	08/14/01	Koh	Tool Services Layer for Provide Service Functions in Conjunction				

Functions

and Medium

Experiment Management System, Method

Feedback Control of a Chemical Mechanical

Polishing Device Providing Manipulation of

Control of Chemical Mechanical Polishing Pad Conditioner Directional Velocity to

Feedforward and Feedback Control for

Conditioning of Chemical Mechanical

In Situ Sensor Based Control of

Removal Rate Profiles

DATE CONSIDERED

Improve Pad Life

Polishing Pad

Semiconductor Processing Procedure

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

Krishnamurthy et al.

Shanmugasundram

Shanmugasundram

et al.

et al.

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Paik

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EXAMINER

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449) APPLICANT Alexander T. SCHWARM et al. FILING DATE August 1, 2003 ATTY. DOCKET NO. 10/632,107

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	10/084,092	02/28/02	Arackaparambil et al.	Computer Integrated Manufacturing Techniques		
	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements		
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	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing		
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor- Related Entities		
	10/173,108	06/18/02	Shanmugasundram et al.	Integrating Tool, Module, and Fab Level Control		
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	10/393,531	03/21/03	Shanmugasundram et al.	Copper Wiring Module Control		
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